

Form PTO-1595 (Rev. 09/04)  
OMB No. 0651-0027 (exp. 6/30/2005)

U.S. DEPARTMENT OF COMMERCE  
United States Patent and Trademark Office

### RECORDATION FORM COVER SHEET PATENTS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

**1. Name of conveying party(ies)/Execution Date(s):**  
 YASUHISA NAKAJIMA (06/03/2010),  
 HIDEKAZU KIKUCHI (06/03/2010),  
 TAKEHIKO SAITOU (06/03/2010),

Execution Date(s) in parentheses after inventor name

Additional name(s) of conveying party(ies) attached?  Yes  No

**2. Name and address of receiving party(ies)**

Name: SONY CORPORATION

Internal Address: \_\_\_\_\_

Street Address:  
 1-7-1 Konan, Minato-ku  
 Tokyo  
 108-0075  
 JAPAN

City: \_\_\_\_\_

State: \_\_\_\_\_

Country: \_\_\_\_\_ Zip: \_\_\_\_\_

Additional name(s) & address(es) attached?  Yes  No

**3. Nature of Conveyance:**

Assignment  Merger

Security Agreement  Change of Name

Government Interest Assignment

Executive Order 9424, Confirmatory License

Other \_\_\_\_\_

**4. Application or patent number(s):**  This document is being filed together with a new application.

A. Patent Application No.(s)  
 12/312,352

B. Patent No.(s)

Additional numbers attached?  Yes  No

**6. Total number of applications and patents involved:**

**5. Name and address to whom correspondence concerning document should be mailed:**

Name: Dennis M. Smid, Esq.  
 LERNER, DAVID, LITTENBERG,  
 KRUMHOLZ & MENTLIK, LLP

Internal Address: Atty. Dkt.: SONYJP 3.3-1577

Street Address: 600 South Avenue West

City: Westfield

State: NJ Zip: 07090

Phone Number: (908) 518-6374

Fax Number: (908) 654-0415

Email Address: dsmid@jdkm.com

**7. Total fee (37 CFR 1.21(h) & 3.41) \$** 40.00

Authorized to be charged by credit card

Authorized to be charged to deposit account

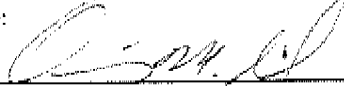
Enclosed

None required (government interest not affecting title)

**8. Payment Information**

a. Credit Card Last 4 Numbers \_\_\_\_\_  
 Expiration Date \_\_\_\_\_

b. Deposit Account Number 12-1095  
 Authorized User Name Dennis M. Smid, Esq.

**9. Signature:**  \_\_\_\_\_ June 16, 2010 \_\_\_\_\_  
 Signature Date

Dennis M. Smid, Esq. - 34,930 Total number of pages including cover sheet, attachments, and documents.   
 Name of Person Signing

CH \$40.00 121095 12312362

RECORDATION FORM COVER SHEET <b>(continued)</b>					
Form PTO-1595					
<b>Additional Conveying Party(ies)/Execution Date(s) (1. Continued):</b>  Shigehiro Kawai (06/03/2010), and Masaki Kitano (06/09/2010)					
<b>Additional Assignees (2. Continued):</b>  Assignee Name: _____ Internal Address: _____ Street Address: _____  City: _____ State: _____ Country: _____ Zip: _____					
Assignee Name: _____ Internal Address: _____ Street Address: _____  City: _____ State: _____ Country: _____ Zip: _____					
Assignee Name: _____ Internal Address: _____ Street Address: _____  City: _____ State: _____ Country: _____ Zip: _____					
<b>Additional Applications and/or Patents (4. Continued):</b>  <table style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 50%; border-right: 1px solid black; padding: 5px; vertical-align: top;">               Additional Patent Application Numbers                4A. Continued:             </td> <td style="width: 50%; padding: 5px; vertical-align: top;">               Additional Patent Numbers                4B. Continued:             </td> </tr> <tr> <td colspan="2" style="text-align: center; padding: 10px;">               Additional numbers attached?    <input type="checkbox"/> Yes    <input type="checkbox"/> No             </td> </tr> </table>		Additional Patent Application Numbers 4A. Continued:	Additional Patent Numbers 4B. Continued:	Additional numbers attached? <input type="checkbox"/> Yes <input type="checkbox"/> No	
Additional Patent Application Numbers 4A. Continued:	Additional Patent Numbers 4B. Continued:				
Additional numbers attached? <input type="checkbox"/> Yes <input type="checkbox"/> No					

Docket No.: SONY/IP 3,3-1577  
Sony Ref. No.: S87P1876US00

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in:

ELECTRONIC APPARATUS AND CABLE DEVICE

for which an International Application was filed on 07 November 2007, PCT/JP2007/071665, designating the United States.

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, my entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the application number and filing date of this application in the spaces that follow: Application Number: \_\_\_\_\_; Filing Date: \_\_\_\_\_

This assignment executed on the dates indicated below.

<u>Yoshihisa NAKAJIMA</u>	_____
Name of First or Sole Inventor	Execution Date of U.S. Patent Application
<u>Konopawa, Japan</u>	_____
Residence of First or Sole Inventor	
<u>Yoshihisa Nakajima</u>	<u>3 June, 2010</u>
Signature of First or Sole Inventor	Date of this Assignment

Docket No.: SONYJP 3.3-1577  
Sony Ref. No.: S07P187SUS00  
Page 2

Hidekazu KIKUCHI

Name of Second Joint Inventor

Execution Date of U.S. Patent Application

Kanagawa, Japan

Residence of Second Joint Inventor

Signature of Second Joint Inventor

Date of this Assignment

Takehiko SAITOU

Name of Third Joint Inventor

Execution Date of U.S. Patent Application

Tokyo, Japan

Residence of Third Joint Inventor

Signature of Third Joint Inventor

Date of this Assignment

Shuichiro KAWAI

Name of Fourth Joint Inventor

Execution Date of U.S. Patent Application

Tokyo, Japan

Residence of Fourth Joint Inventor

Signature of Fourth Joint Inventor

Date of this Assignment

Masaki KITANO

Name of Fifth Joint Inventor

Execution Date of U.S. Patent Application

Tokyo, Japan

Residence of Fifth Joint Inventor

10-05-28; 03:40PM; 南山国際特許事務所  
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# 9/10

008

Docket No.: SONYJP 3,3-1577  
Sony Ref. No.: S07P187GUS00

ASSIGNMENT

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NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, my entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

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This assignment executed on the dates indicated below.

Yasuhisa NAKAJIMA

Name of First or Sole Inventor

Execution Date of U.S. Patent Application

Kanagawa, Japan

Residence of First or Sole Inventor

\_\_\_\_\_  
Signature of First or Sole Inventor

\_\_\_\_\_  
Date of this Assignment

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Docket No.: SONYJP3.3-1577  
Sony Ref. No.: S07P1875US00  
Page 2

Hidekazu KIKUCHI

Name of Second Joint Inventor

Execution Date of U.S. Patent Application

Kanagawa, Japan

Residence of Second Joint Inventor

*Hidekazu Kikuchi*

June 3, 2010

Signature of Second Joint Inventor

Date of this Assignment

Takehiko SAITOU

Name of Third Joint Inventor

Execution Date of U.S. Patent Application

Tokyo, Japan

Residence of Third Joint Inventor

Signature of Third Joint Inventor

Date of this Assignment

Shirohito KAWAI

Name of Fourth Joint Inventor

Execution Date of U.S. Patent Application

Tokyo, Japan

Residence of Fourth Joint Inventor

Signature of Fourth Joint Inventor

Date of this Assignment

Masaki KITANO

Name of Fifth Joint Inventor

Execution Date of U.S. Patent Application

Tokyo, Japan

Residence of Fifth Joint Inventor

USPTO FORM

2010年 6月10日 15時52分

NO. 1013 P. 12

Docket No.: SONYJP 3.3-1577  
Sony Ref. No.: S07P1876US00

ASSIGNMENT

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And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

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Yasuhisa NAKAJIMA  
Name of First or Sole Inventor

\_\_\_\_\_  
Execution Date of U.S. Patent Application

Kanagawa, Japan  
Residence of First or Sole Inventor

\_\_\_\_\_  
Signature of First or Sole Inventor

\_\_\_\_\_  
Date of this Assignment

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PATENT

10-06-11; 06:10PM; 南青山 法律事務所

Lerner, David

; 0335052852

# 13/ 13

2010年 6月10日 15時52分

NO. 1013 P. 13

Docket No.: SONYJP 3,3-1577

Sony Ref. No.: S07P1875US00

Page 2

Hidekazu KIKUCHI

Name of Second Joint Inventor

Execution Date of U.S. Patent Application

Kanagawa, Japan

Residence of Second Joint Inventor

Signature of Second Joint Inventor

Date of this Assignment

Takemitsu SAITOU

Name of Third Joint Inventor

Execution Date of U.S. Patent Application

Tokyo, Japan

Residence of Third Joint Inventor

*Takemitsu Saito*

3 June 2010

Signature of Third Joint Inventor

Date of this Assignment

Shigehiro KAWAI

Name of Fourth Joint Inventor

Execution Date of U.S. Patent Application

Tokyo, Japan

Residence of Fourth Joint Inventor

*Shigehiro Kawai*

3 June 2010

Signature of Fourth Joint Inventor

Date of this Assignment

Masaki KITANO

Name of Fifth Joint Inventor

Execution Date of U.S. Patent Application

Tokyo, Japan

Residence of Fifth Joint Inventor

02509, I Doc

PATENT

06/11/2010 REEL: 024548 FRAME: 0859 13



Docket No.: SONYJP 3.3-1577  
Sony Ref. No.: S07P1876US00

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\_\_\_\_\_  
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Kanagawa, Japan  
Residence of First or Sole Inventor

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Signature of First or Sole Inventor

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Docket No.: SONYJP 3.3-1577  
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Page 2

Hidekazu KIKUCHI

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Signature of Fourth Joint Inventor

Date of this Assignment

Masaki KITANO

Name of Fifth Joint Inventor

Execution Date of U.S. Patent Application

Tokyo, Japan

Residence of Fifth Joint Inventor

*Masaki Kitano*

*June 9. 2010*

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